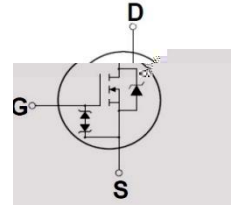
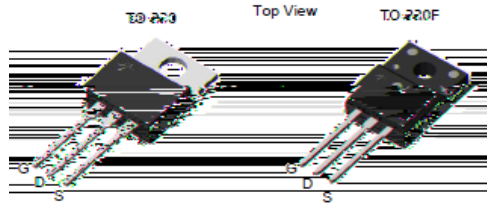


N-channel MOSFET

## Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification

$BV_{DSS}$	$I_D$	$R_{DS(on)}$
500V	4.5A	<1.5Ω



Device	Package	Marking	Remark
TMP830Z / TMPF830Z	TO-220 / TO-220F	TMP830Z/ TMPF830Z	RoHS
TMP830ZG / TMPF830ZG	TO-220 / TO-220F	TMP830ZG/ TMPF830ZG	Halogen Free

## Absolute Maximum Ratings

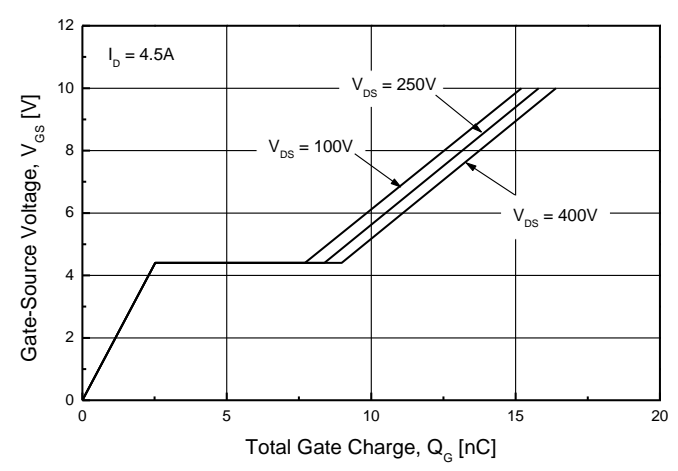
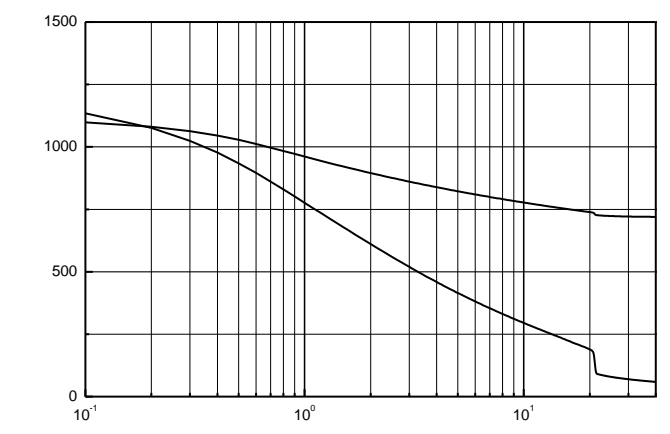
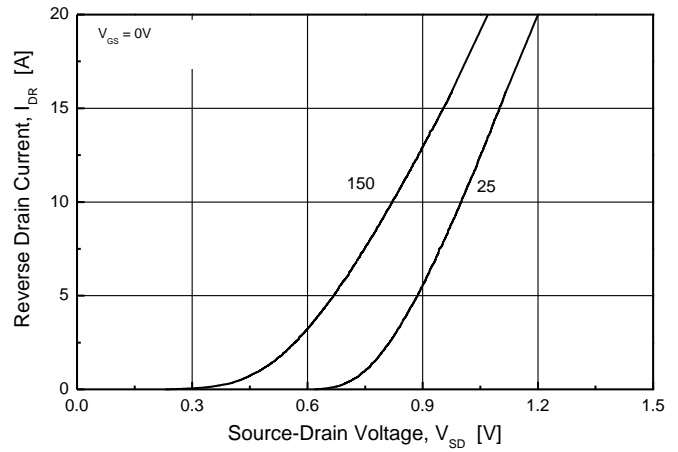
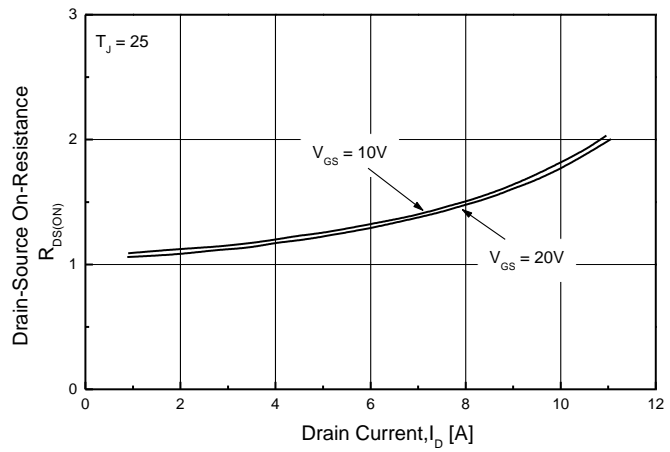
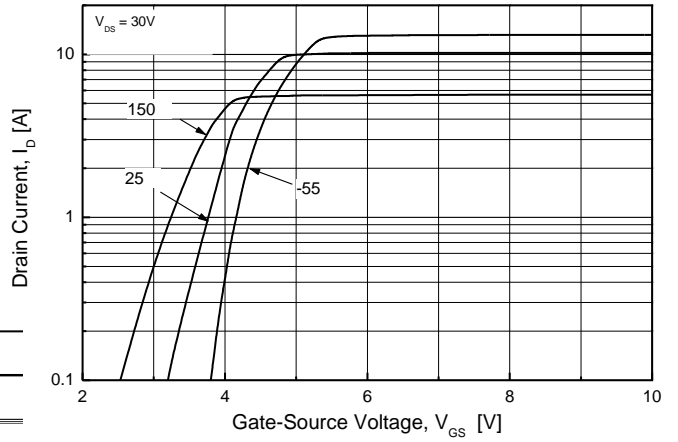
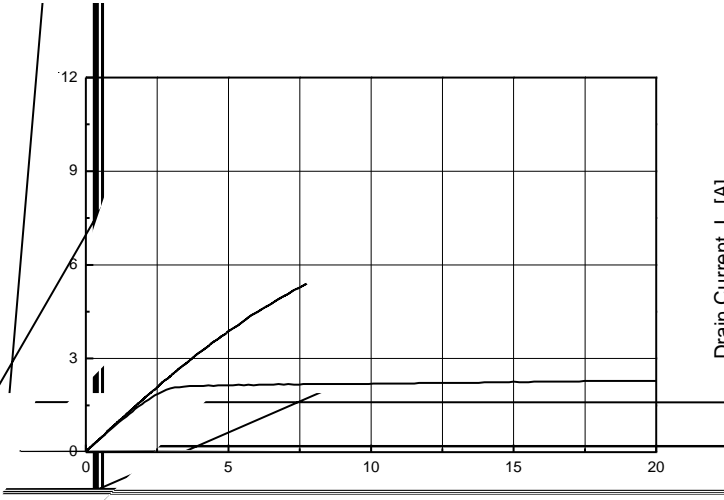
Parameter	Symbol	TMP830Z(G)	TMPF830Z(G)	Unit	
Drain-Source Voltage	$V_{DSS}$	500		V	
Gate-Source Voltage	$V_{GS}$	30		V	
Continuous Drain Current	$I_D$	$T_C = 25$	4.5	4.5 *	A
		$T_C = 100$	3.1	3.1	A
Pulsed Drain Current (Note 1)	$I_{DM}$	18	18	A	
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	282		mJ	
Repetitive Avalanche Current (Note 1)	$I_{AR}$	4.5		A	
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	9.84		mJ	
Power Dissipation	$P_D$	$T_C = 25$	98.4	32.9	W
		Derate above 25	0.78	0.26	W/
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150			
Maximum lead temperature for soldering purposes,	$T_L$	300			

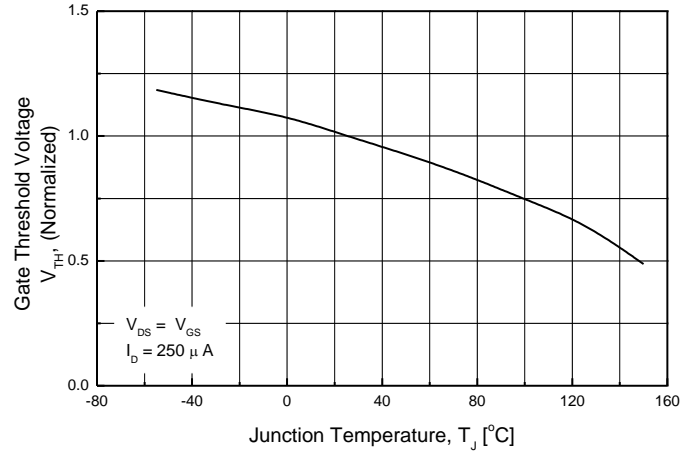
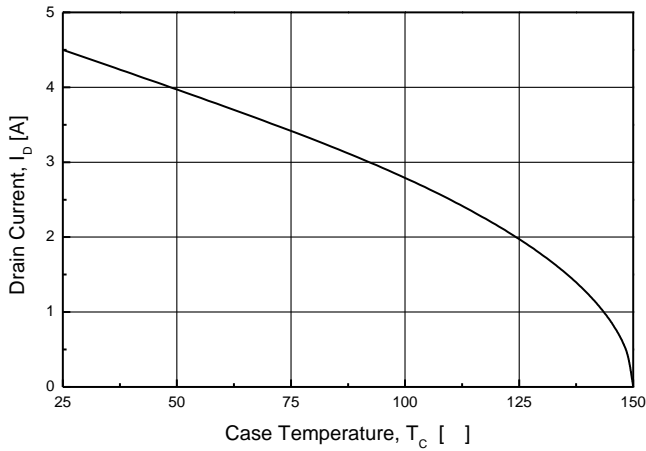
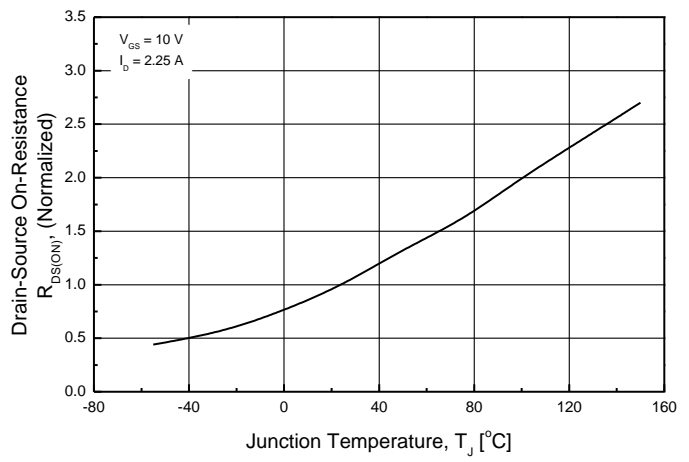
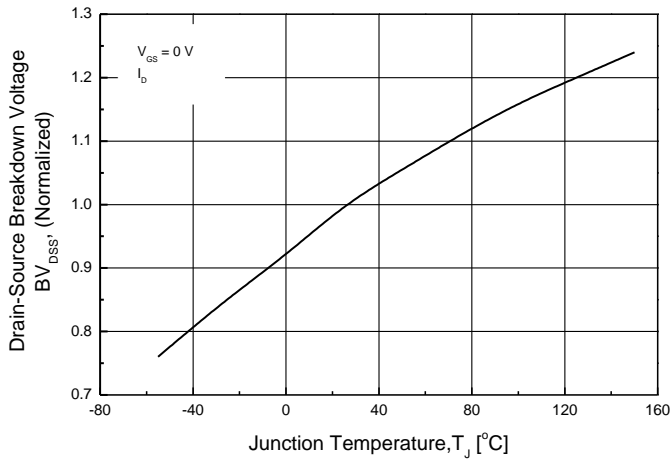
\* Limited only by maximum junction temperature

## Thermal Characteristics

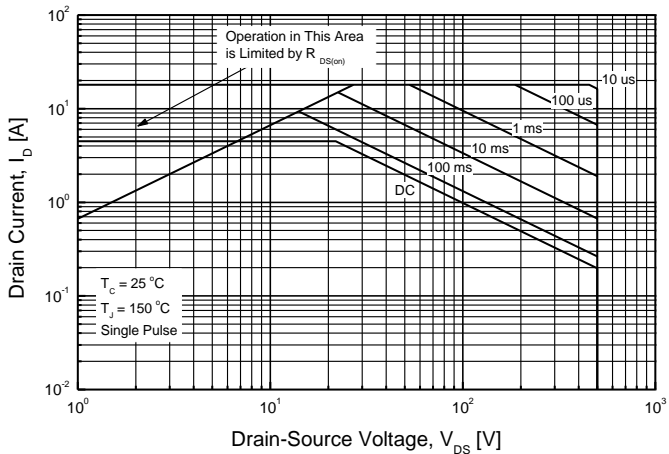
Parameter	Symbol	TMP830Z(G)	TMPF830Z(G)	Unit
Maximum Thermal resistance, Junction-to-Case	$R_{\theta JC}$	1.27	3.8	/W
Maximum Thermal resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	62.5	/W



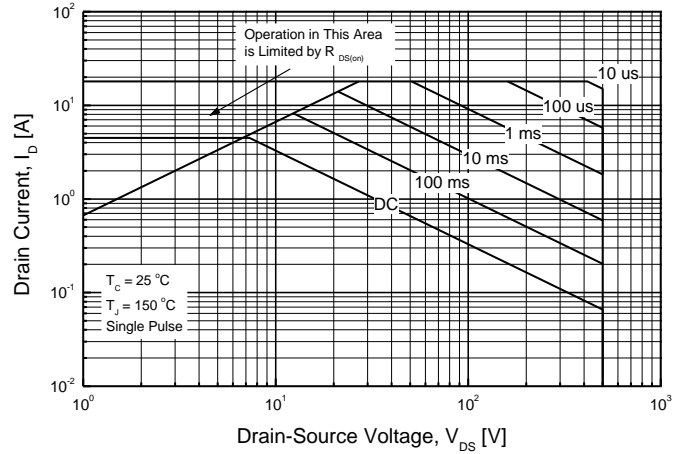




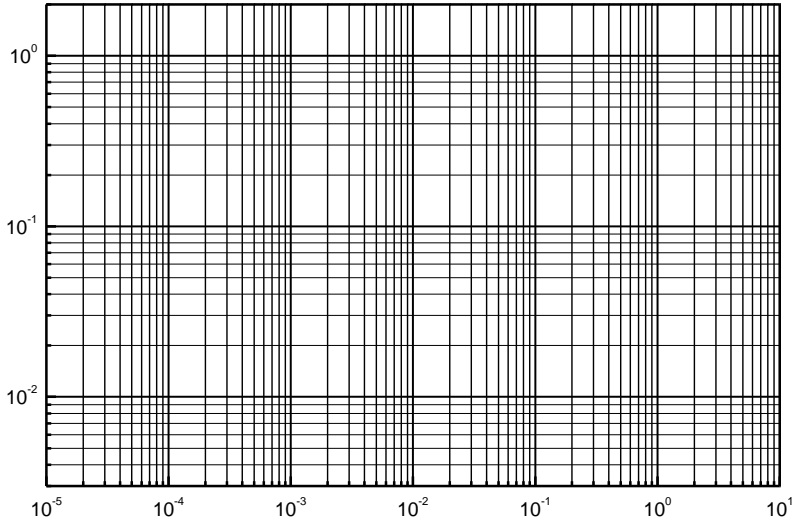
## TMP830Z(G)



## TMPF830Z(G)



TMP830Z(G)



TMPF830Z(G)

